
Preskusne metode za električne materiale, tiskana vezja in druge povezovalne strukture in sestave - 2-630. del: Preskusne metode za osnovne materiale za toga tiskana vezja - Absorpcija vlage po kondicioniranju tlačne posode

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-630: Test methods for base materials for rigid printed boards - Moisture Absorption after pressure vessel conditioning

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Ta slovenski standard je istoveten z: EN IEC 61189-2-630:2018

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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EUROPEAN STANDARD

EN IEC 61189-2-630

NORME EUROPÉENNE

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October 2018

ICS 31.180

English Version

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-630: Test methods for materials for interconnection structures - Moisture absorption after pressure vessel conditioning
(IEC 61189-2-630:2018)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-630: Méthodes d'essai des matériaux pour structures d'interconnexion - Absorption d'humidité après conditionnement dans un récipient sous pression
(IEC 61189-2-630:2018)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-630: Prüfverfahren für Materialien für Verbindungsstrukturen - Feuchteaufnahme nach Druckbehälterbeanspruchung
(IEC 61189-2-630:2018)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-2-630:2018 (E)**European foreword**

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The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2019-04-10
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2021-07-10

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and-assembly - Terms and definitions		-

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INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Test methods for electrical materials, printed board and other interconnection structures and assemblies –
Part 2-630: Test methods for materials for interconnection structures – Moisture absorption after pressure vessel conditioning**

<https://standards.iteh.ai/catalog/standards/sist/61bfc23e-fdef-4831-9a39->

**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –
Partie 2-630: Méthodes d'essai des matériaux pour structures d'interconnexion –
Absorption d'humidité après conditionnement dans un récipient sous pression**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-630: Test methods for materials for interconnection structures –
Moisture absorption after pressure vessel conditioning**

FOREWORD

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International Standard IEC 61189-2-630 has been prepared by IEC technical committee 91: Electronics assembly technology

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1471/CDV	91/1503/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.